BTA208X series D, E and F

GENERAL DESCRIPTION

QUICK REFERENCE DATA

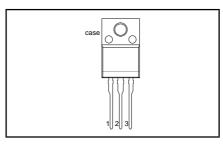
Passivated guaranteed commutation triacs in a full pack, plastic envelope intended for use in motor control circuits or with other highly inductive loads. These devices balance the requirements of commutation performance and gate sensitivity. The "sensitive gate" E series and "logic level" D series are intended for interfacing with low power drivers, including micro controllers.

SYMBOL	PARAMETER	MAX.	MAX.	UNIT
	BTA208X- BTA208X- BTA208X-	600D 600E 600F	- 800E 800F	
V_{DRM}	Repetitive peak off-state voltages	600	800	V
I _{T(RMS)} I _{TSM}	RMS on-state current Non-repetitive peak on-state current	8 65	8 65	A A

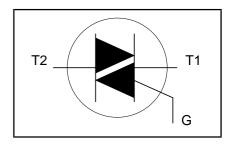
PINNING - SOT186A

PIN	DESCRIPTION				
1	main terminal 1				
2	main terminal 2				
3	gate				
case	isolated				

PIN CONFIGURATION



SYMBOL



LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.		UNIT
V_{DRM}	Repetitive peak off-state voltages		,	-600 600 ¹	-800 800	V
I _{T(RMS)}	RMS on-state current	full sine wave;	-	8		A
I _{TSM}	Non-repetitive peak on-state current	$\begin{array}{l} T_{hs} \leq 73 \ ^{\circ}C \\ \text{full sine wave;} \\ T_{j} = 25 \ ^{\circ}C \ \text{prior to} \\ \text{surge} \end{array}$			_	
		t = 20 ms t = 16.7 ms	-	65		A
l²t dl _⊤ /dt	l ² t for fusing Repetitive rate of rise of on-state current after	t = 10.7 ms t = 10 ms $I_{TM} = 12 \text{ A}; I_G = 0.2 \text{ A};$ $dI_G/dt = 0.2 \text{ A}/\mu\text{s}$	-	72 21 100		Α A²s A/μs
$\begin{matrix} I_{GM} \\ P_{GM} \\ P_{G(AV)} \end{matrix}$	triggering Peak gate current Peak gate power Average gate power	over any 20 ms	-	2 5 0.5		A W W
T_{stg}	Storage temperature Operating junction temperature	period	-40 -	150 125		ů

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¹ Although not recommended, off-state voltages up to 800V may be applied without damage, but the triac may switch to the on-state. The rate of rise of current should not exceed 6 $A/\mu s$.

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ISOLATION LIMITING VALUE & CHARACTERISTIC

 T_{hs} = 25 $^{\circ}C$ unless otherwise specified

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V _{isol}	R.M.S. isolation voltage from all three terminals to external heatsink	f = 50-60 Hz; sinusoidal waveform; R.H. ≤ 65%; clean and dustfree	-	1	2500	V
C _{isol}	Capacitance from T2 to external heatsink	f = 1 MHz	-	10	-	pF

THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
R _{th j-hs}	Thermal resistance junction to heatsink	full or half cycle with heatsink compound without heatsink compound			4.5 6.5	K/W K/W
R _{th j-a}	Thermal resistance junction to ambient	in free air	-	55	-	K/W

STATIC CHARACTERISTICS

 $T_i = 25$ °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.		MAX.		UNIT
		BTA208X-		D	Е	F	
I _{GT}	Gate trigger current ²	V _D = 12 V; I _T = 0.1 A T2+ G+ T2+ G- T2- G-	- - -	5 5 5	10 10 10	25 25 25	mA mA mA
I _L	Latching current	V _D = 12 V; I _{GT} = 0.1 A T2+ G+ T2+ G- T2- G-	- - -	15 25 25	25 30 30	30 40 40	mA mA mA
I _H	Holding current	$V_D = 12 \text{ V}; I_{GT} = 0.1 \text{ A}$	-	15	25	30	mA
V_{GT}	On-state voltage Gate trigger voltage	$I_T = 10 \text{ A}$ $V_D = 12 \text{ V}; I_T = 0.1 \text{ A}$ $V_D = 400 \text{ V}; I_T = 0.1 \text{ A};$	- - 0.25		1.65 1.5 -		V V V
I _D	Off-state leakage current	$T_{j} = 125 ^{\circ}\text{C}$ $V_{D} = V_{DRM(max)}, T_{j} = 125 ^{\circ}\text{C}$	-		0.5		mA

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² Device does not trigger in the T2-, G+ quadrant.

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DYNAMIC CHARACTERISTICS

T_i = 25 °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.			MAX.	UNIT
		BTA208X-	D	Е	F		
dV _D /dt	Critical rate of rise of off-state voltage	V _{DM} = 67% V _{DRM(max)} ; T _j = 110 °C; exponential waveform; gate open circuit	20	60	70	-	V/μs
dl _{com} /dt	Critical rate of change of commutating current	$V_{DM} = 400 \text{ V}; T_j = 125 ^{\circ}\text{C};$ $I_{T(RMS)} = 8 \text{ A};$ $dV_{com}/dt = 10 \text{V}/\mu\text{s}; \text{ gate}$ open circuit	2	5	14	-	A/ms
dl _{com} /dt	Critical rate of change of commutating current	$V_{DM} = 400 \text{ V}; T_j = 125 ^{\circ}\text{C};$ $I_{T(RMS)} = 8 \text{ A};$ $dV_{com}/dt = 0.1 \text{V}/\mu\text{s}; \text{ gate}$ open circuit	6	10	20	-	A/ms

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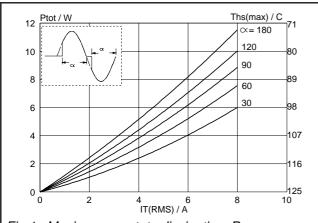


Fig.1. Maximum on-state dissipation, P_{tot} , versus rms on-state current, $I_{T(RMS)}$, where $\alpha =$ conduction angle.

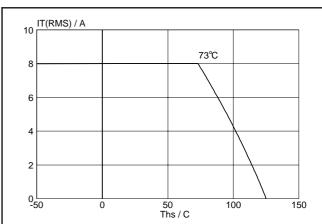


Fig.4. Maximum permissible rms current $I_{\text{T(RMS)}}$, versus heatsink temperature T_{hs} .

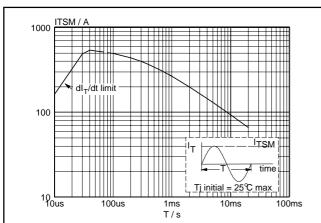


Fig.2. Maximum permissible non-repetitive peak on-state current I_{TSM} , versus pulse width t_p , for sinusoidal currents, $t_p \le 20$ ms.

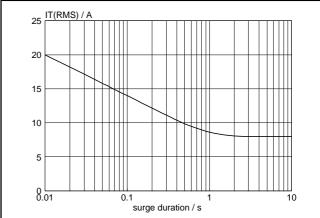


Fig.5. Maximum permissible repetitive rms on-state current $I_{T(RMS)}$, versus surge duration, for sinusoidal currents, f = 50 Hz; $T_{hs} \le 73$ °C.

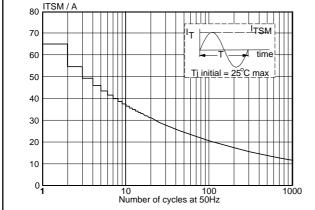


Fig.3. Maximum permissible non-repetitive peak on-state current I_{TSM} , versus number of cycles, for sinusoidal currents, f = 50 Hz.

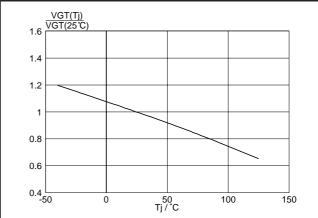
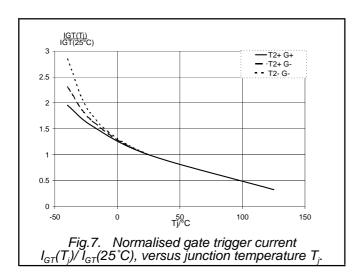
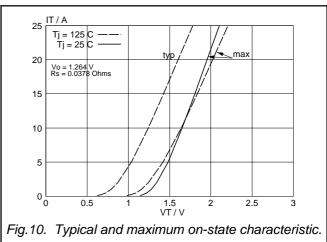


Fig.6. Normalised gate trigger voltage $V_{GT}(T_j)/V_{GT}(25^{\circ}C)$, versus junction temperature T_{j} .

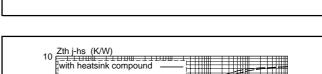
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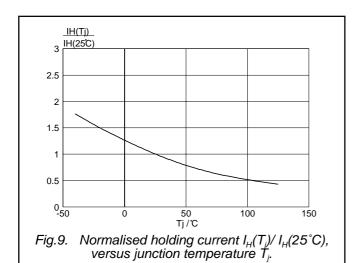


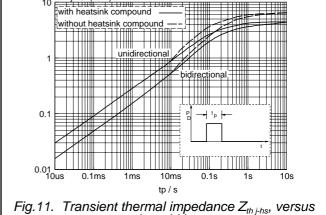


3
2.5
2
1.5
0.5
0-50
0 0 50
0 100
150
Fig. 8. Normalised latching current $I_L(T_i)/I_L(25^{\circ}C)$,

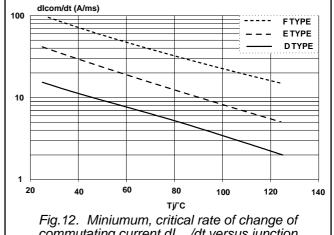
versus junction temperature T_i







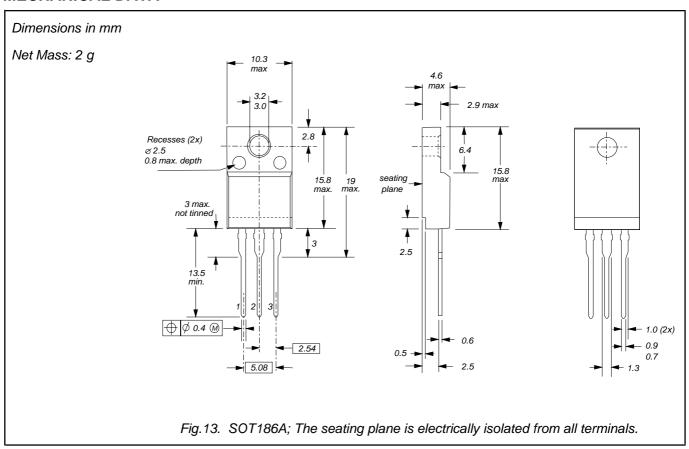
pulse width t_p .



rig.12. Miniumum, critical rate of change of commutating current dl_{com}/dt versus junction temperature, $dV_{com}/dt = 20V/\mu s$

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MECHANICAL DATA



- Notes
 1. Refer to mounting instructions for F-pack envelopes.
 2. Epoxy meets UL94 V0 at 1/8".

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DEFINITIONS

DATA SHEET STATU	DATA SHEET STATUS						
DATA SHEET STATUS ³	PRODUCT STATUS ⁴	DEFINITIONS					
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice					
Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product					
Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Changes will be communicated according to the Customer Product/Process Change Notification (CPCN) procedure SNW-SQ-650A					

Limiting values

Limiting values are given in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of this specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information

Where application information is given, it is advisory and does not form part of the specification.

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³ Please consult the most recently issued datasheet before initiating or completing a design.

⁴ The product status of the device(s) described in this datasheet may have changed since this datasheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.